

ABSTRACT

An upper mold (13), a lower mold (14), a middle mold (15), and a release film (17) are used in a method of resin sealing of an electronic component (2). The release film (17) is sandwiched between the lower mold (14) and the middle mold (15) and held under a prescribed tension to cover a cavity (16) of the lower mold (14). A cavity side surface (54b) is also covered with the release film (17). Therefore, releasability of a cured resin (10) from the cavity side surface (54b) is increased. As a result, the cured resin (10) is prevented from being damaged near the cavity side surface (54b).